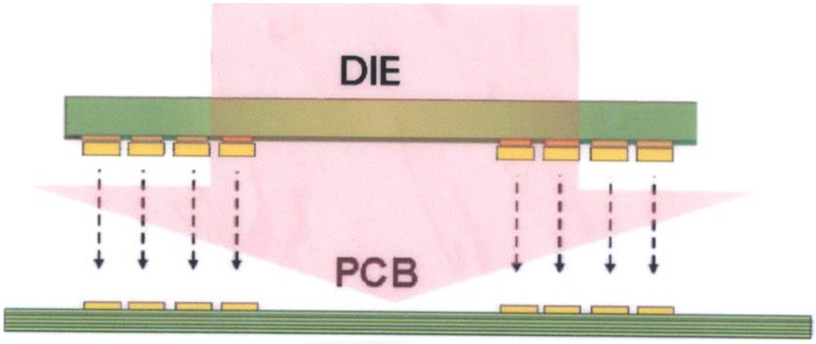
FLIP CHIP TECHNOLOGY

➔ The device mounts without encapsulation directly on the PCB.



➔ Advantages

- ○ Reduction of physical space on the PCB.
- ○ Reduction of connections. The foot or ball is replaced by small connections (≈100um) and the internal connection structure is removed.
- ○ Cost reduction. Few modifications over the standard surface mount process.